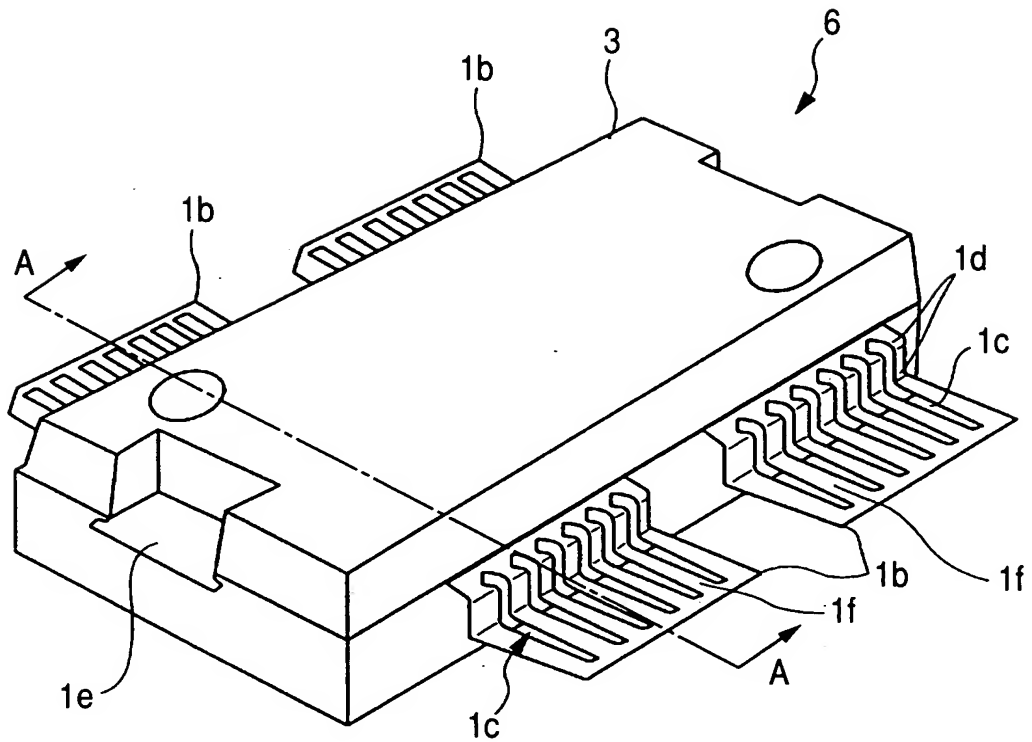


FIG. 1



1b: OUTER LEAD

1c: SLIT

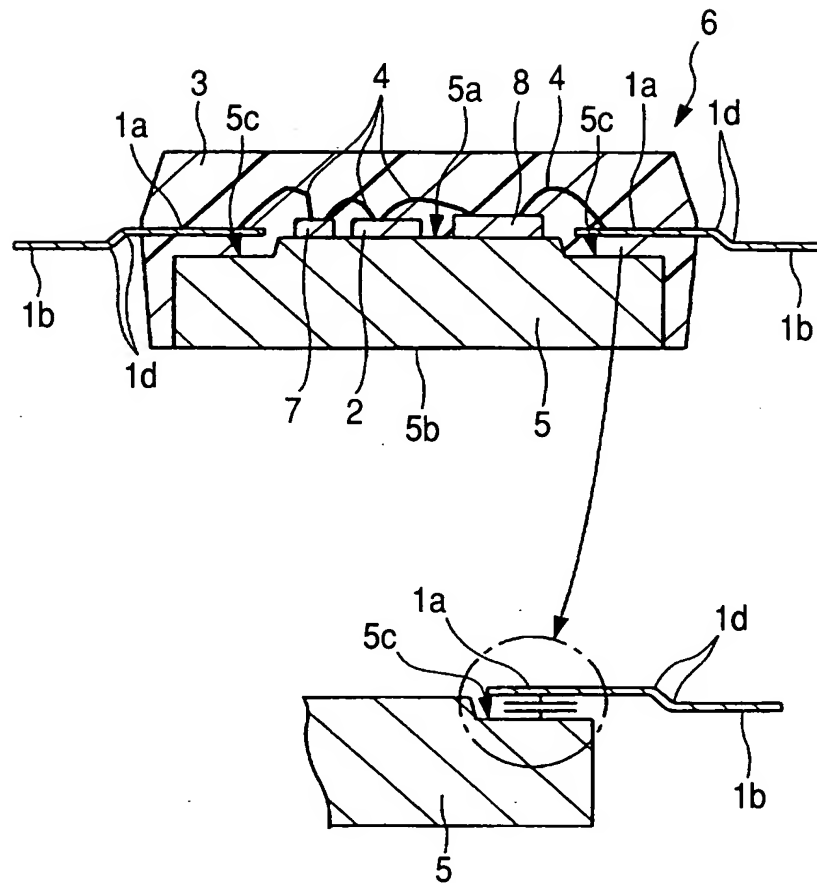
1d: BENT PORTION

1e: METAL PLATE
SUSPENDING PORTION

1f: OUTER-LEAD SPLIT PORTION

3: MOLDING BODY

6: MOSFET
(SEMICONDUCTOR DEVICE)

FIG. 2

- 1a: INNER LEAD
- 2: FET CHIP
- 4: WIRE (METAL WIRE)
- 5: HEAT SINK (METAL PLATE)
- 5c: DEPRESSED PORTION
- 7: MOS-C CHIP

FIG. 3

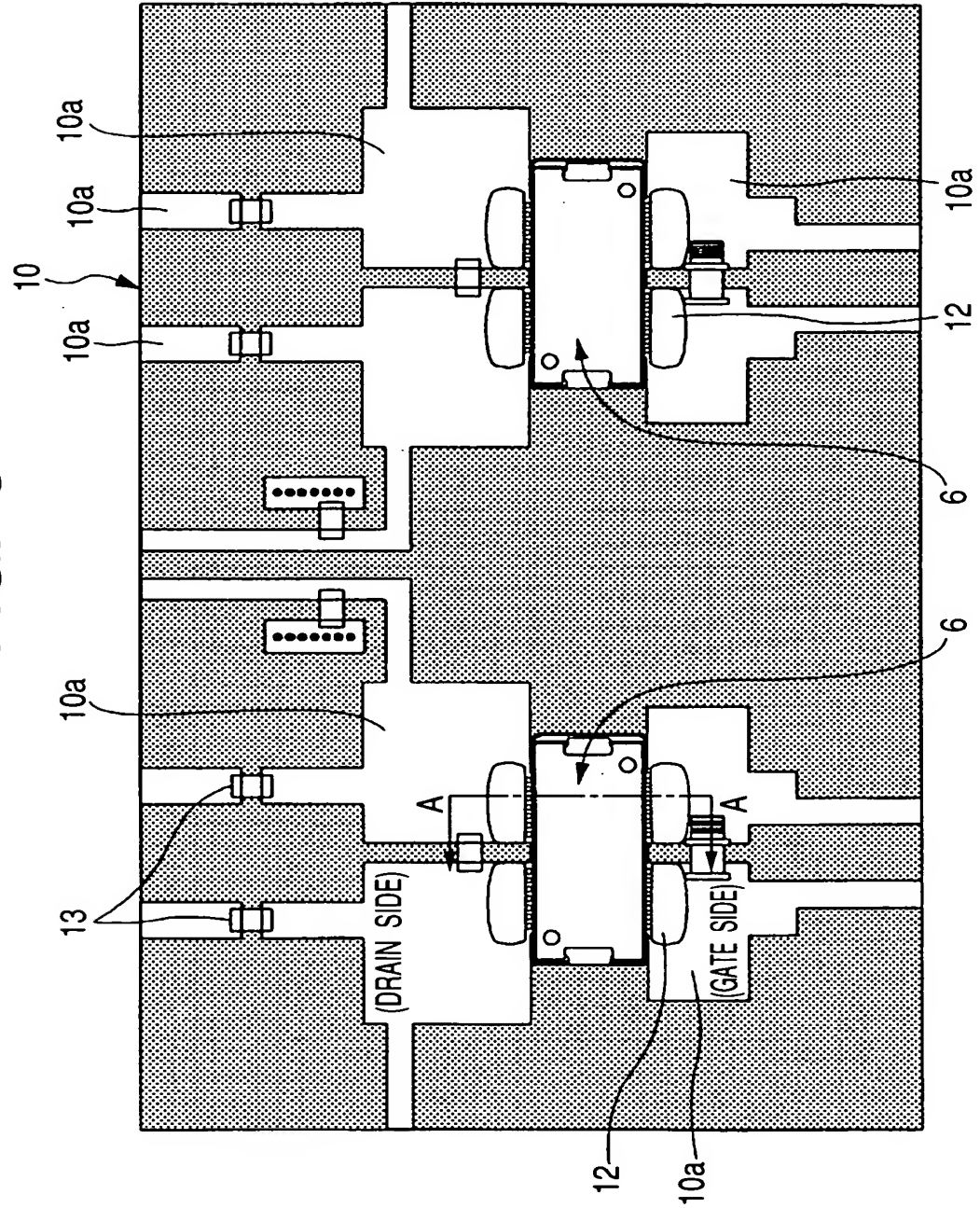


FIG. 4

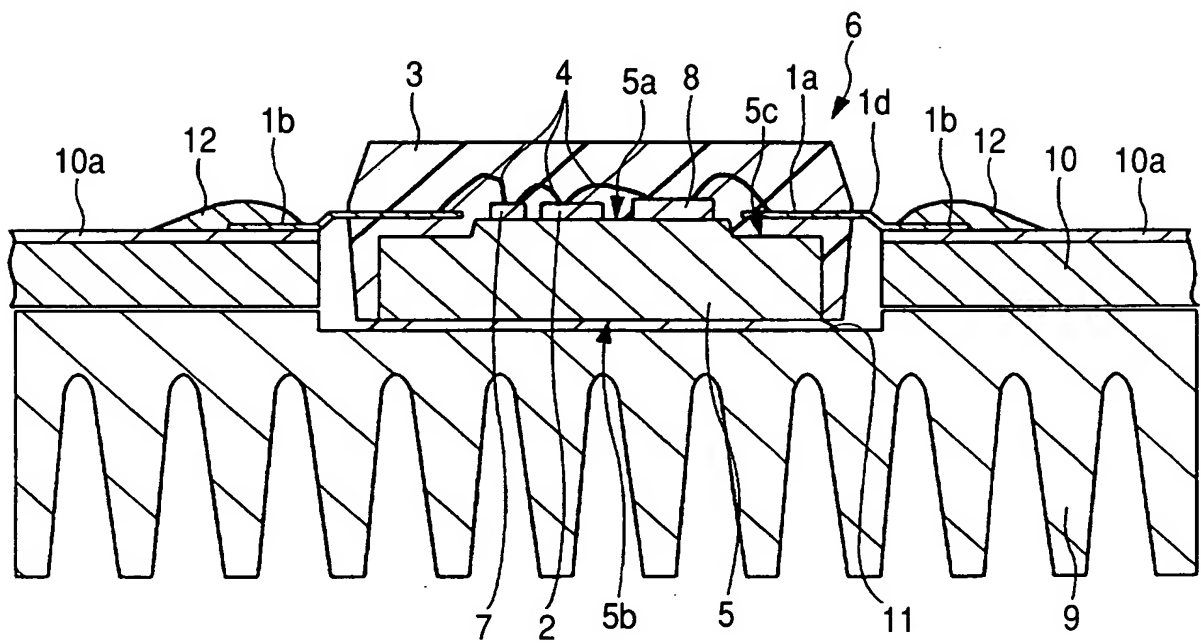


FIG. 5

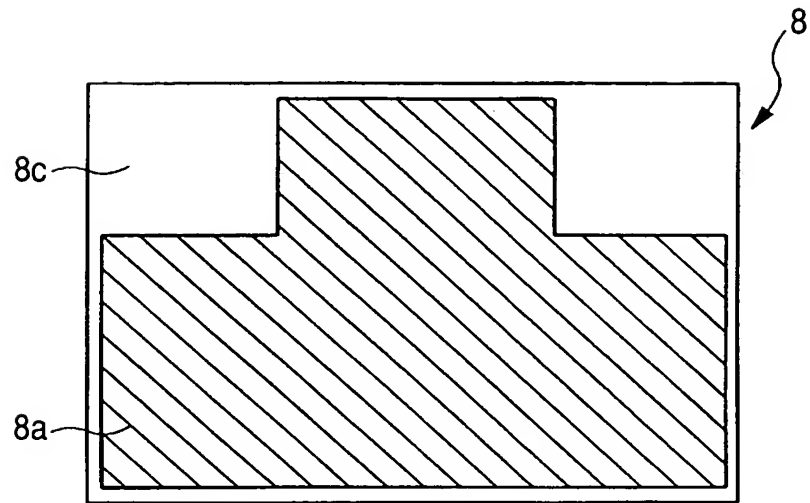


FIG. 6

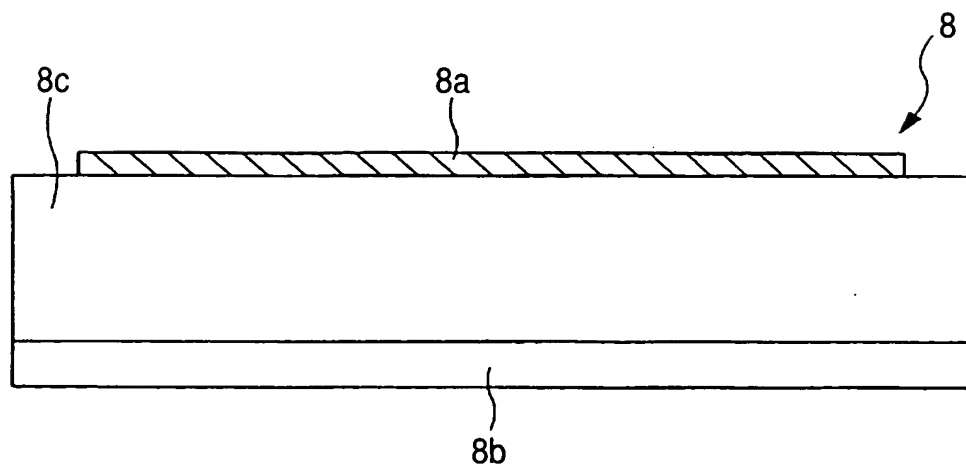


FIG. 7

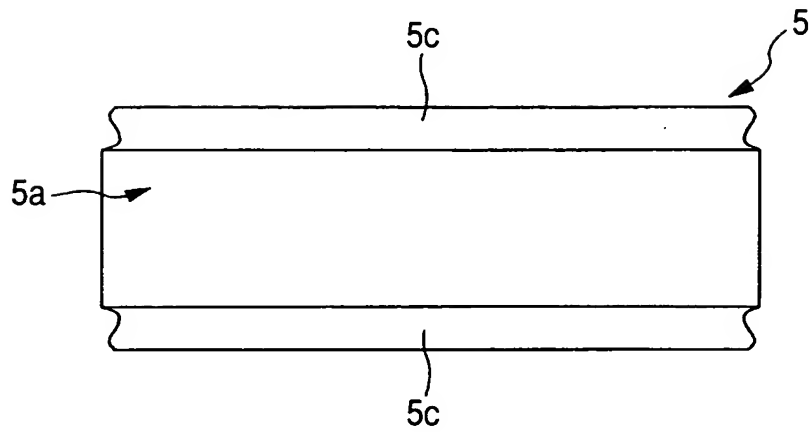


FIG. 8

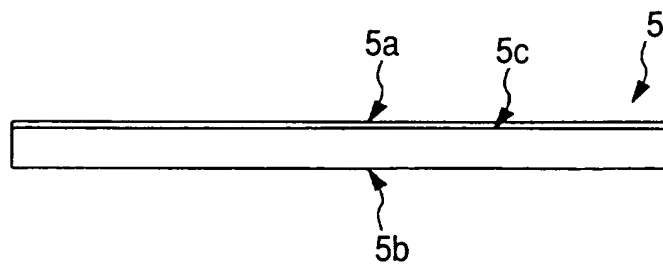


FIG. 9

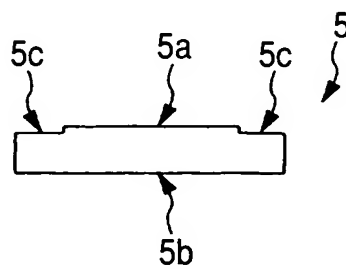


FIG. 10

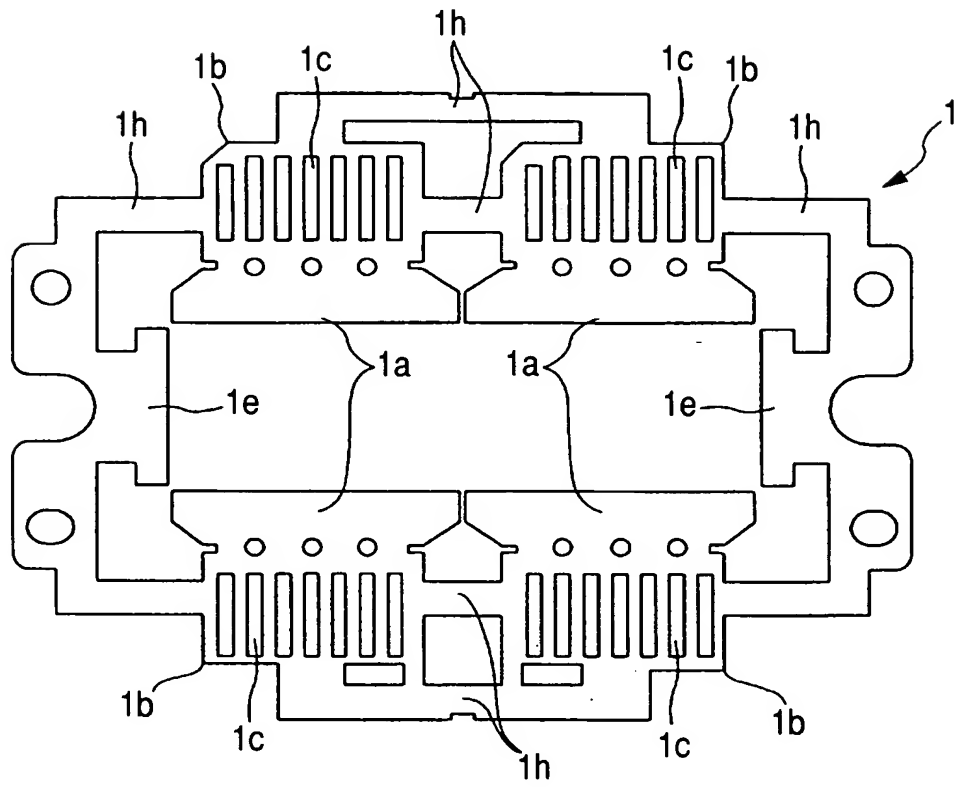


FIG. 11



FIG. 12



FIG. 13

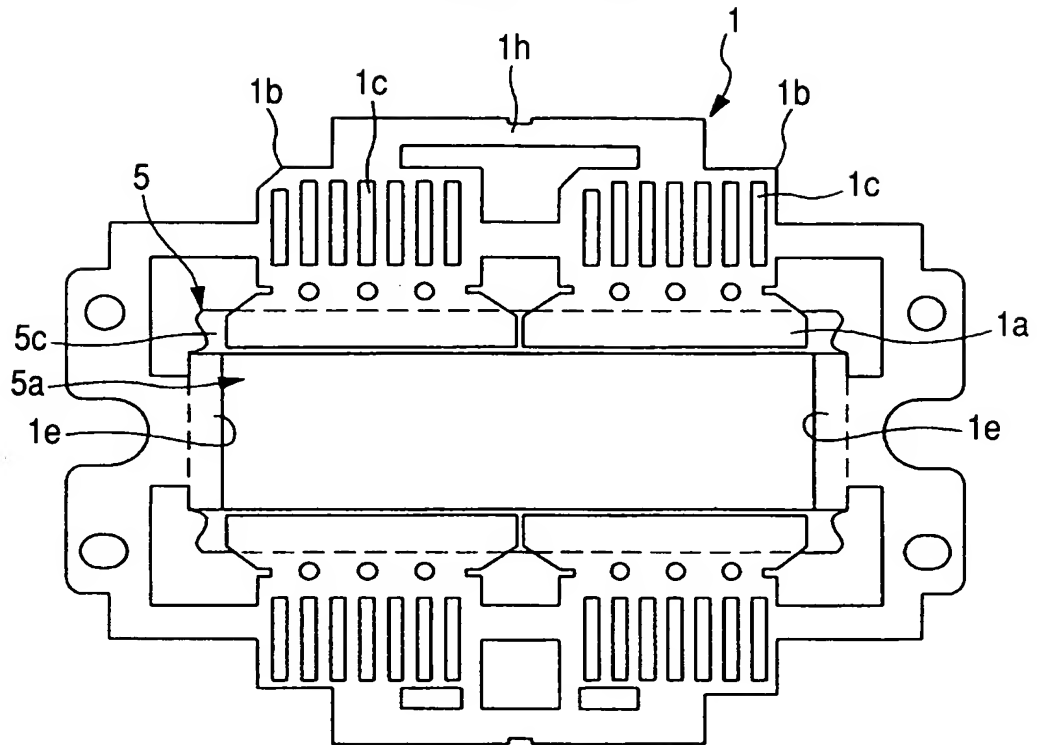


FIG. 14

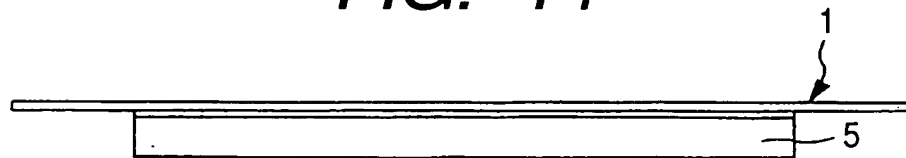


FIG. 15

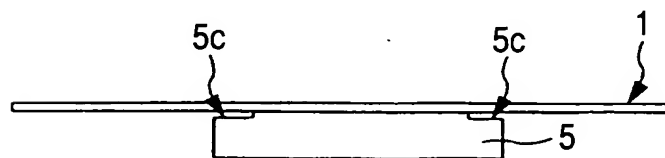


FIG. 16

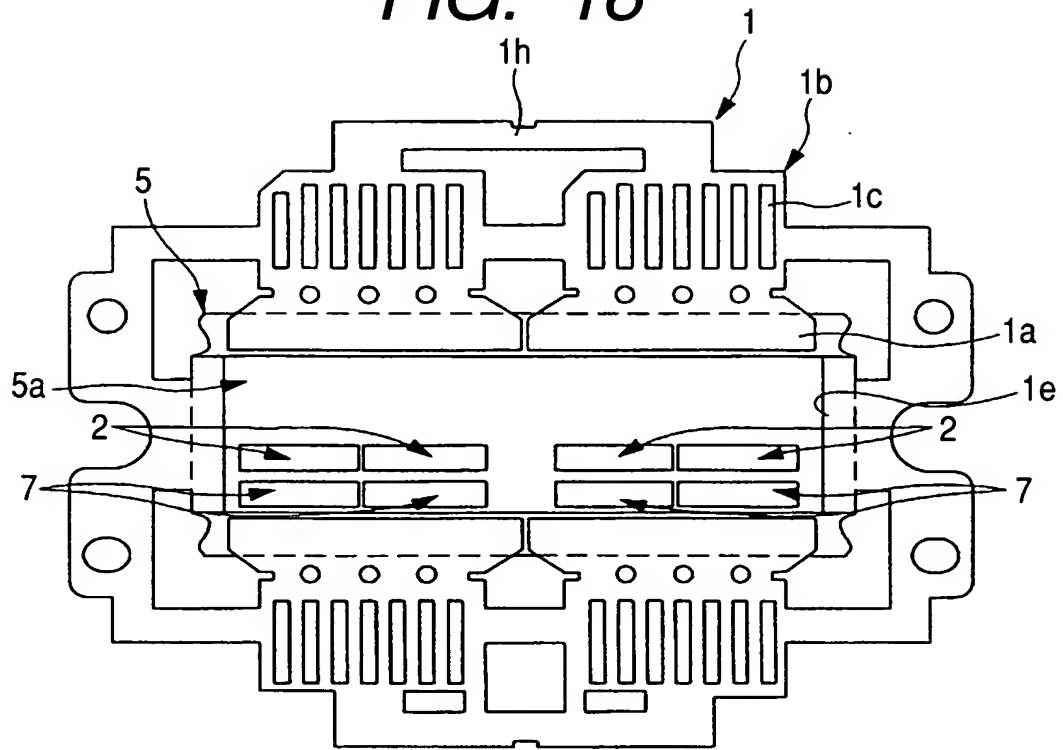


FIG. 17

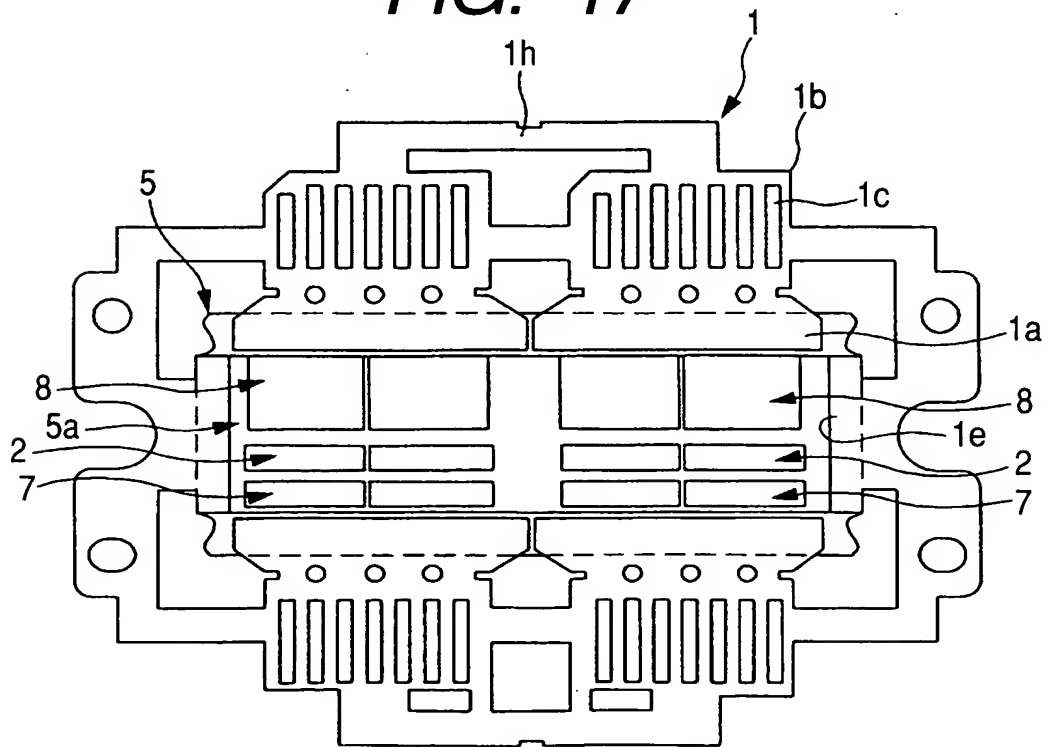


FIG. 18

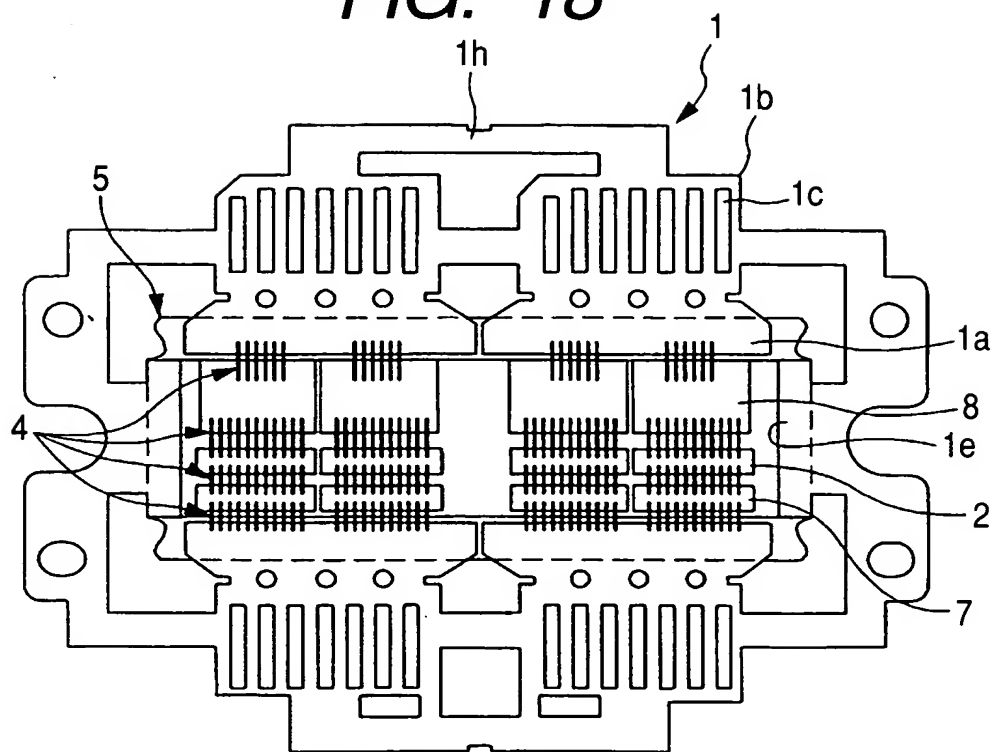


FIG. 19

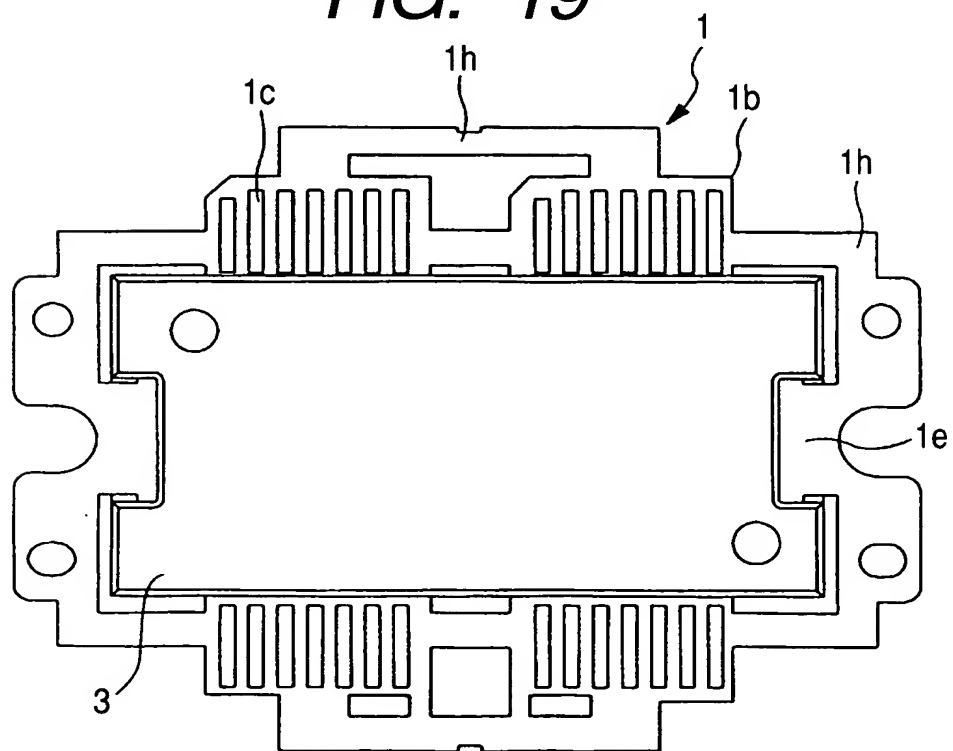


FIG. 20

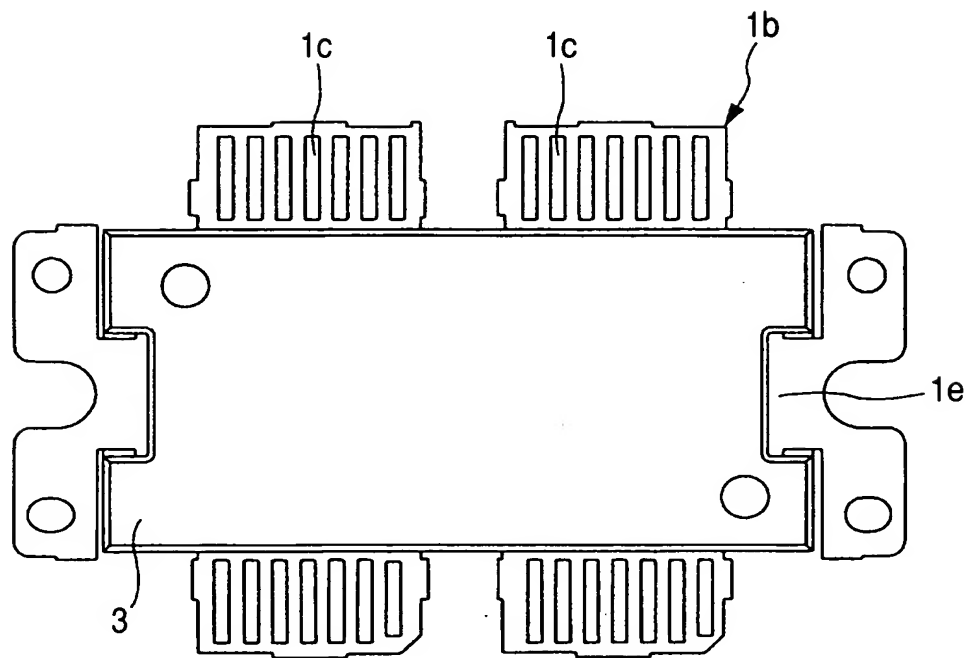


FIG. 21

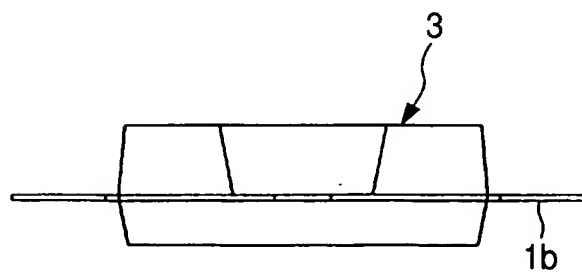


FIG. 22

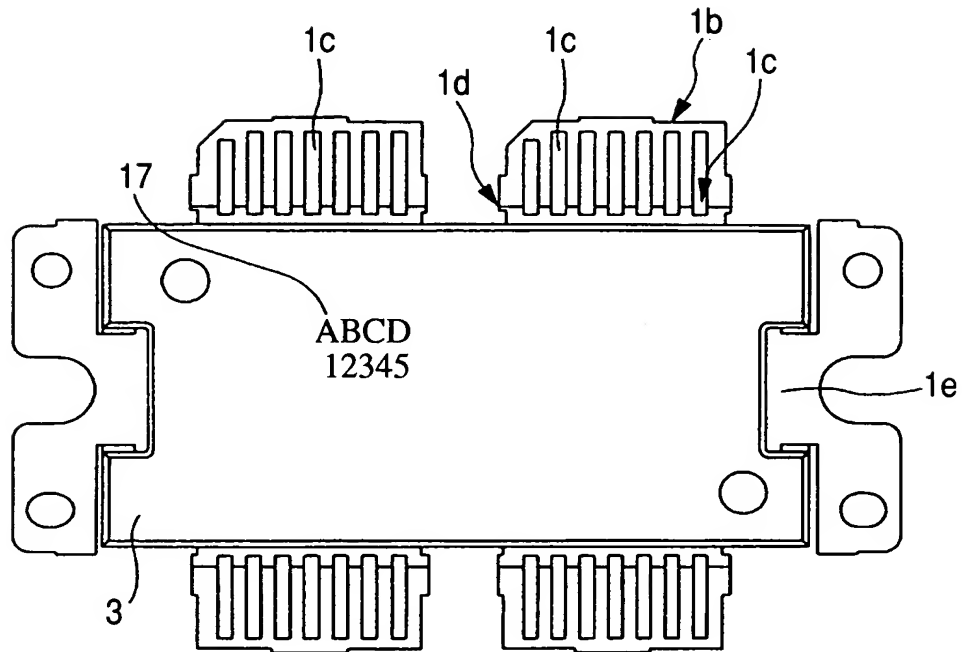


FIG. 23

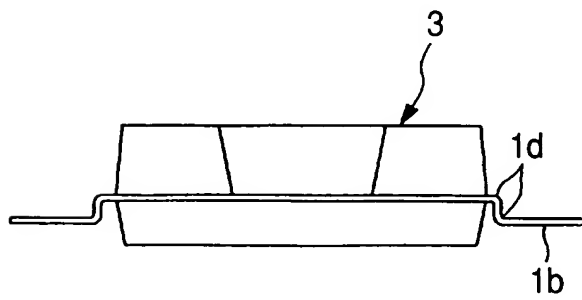


FIG. 24

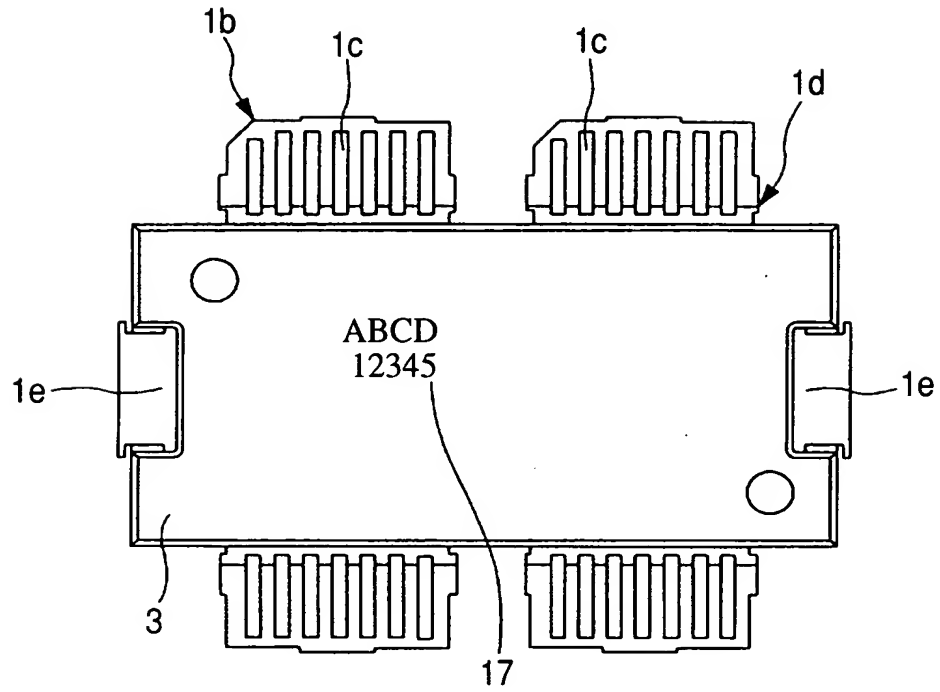


FIG. 25

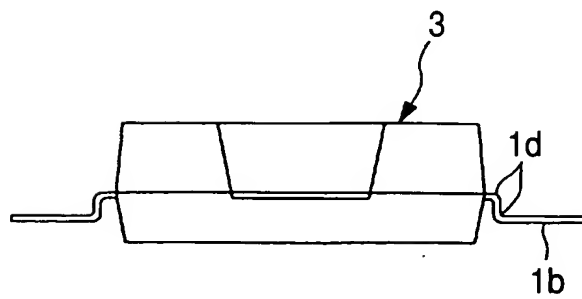


FIG. 26

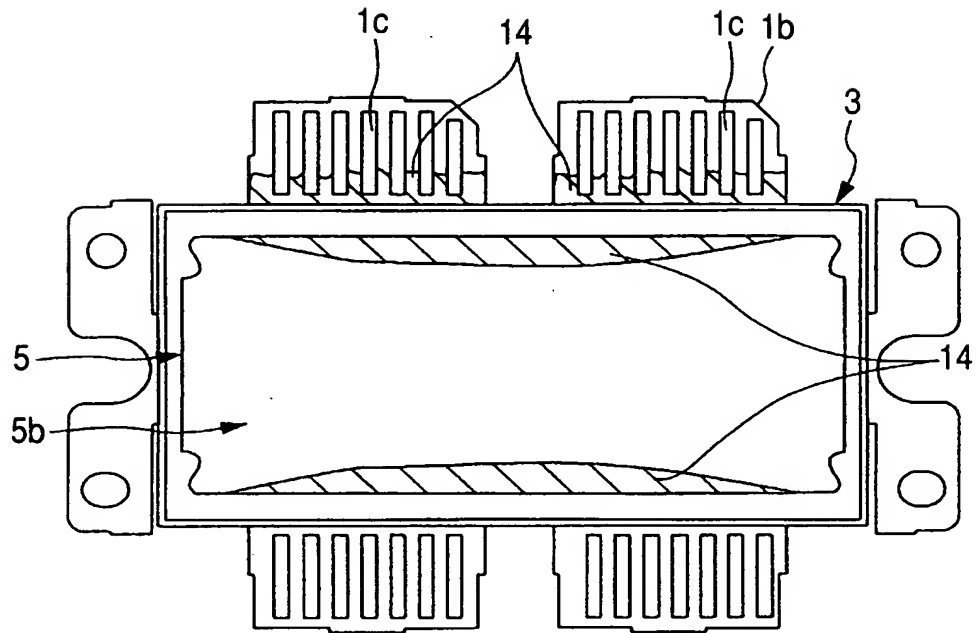
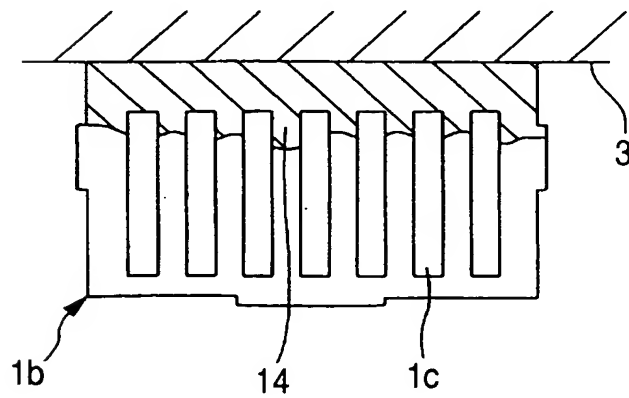


FIG. 27



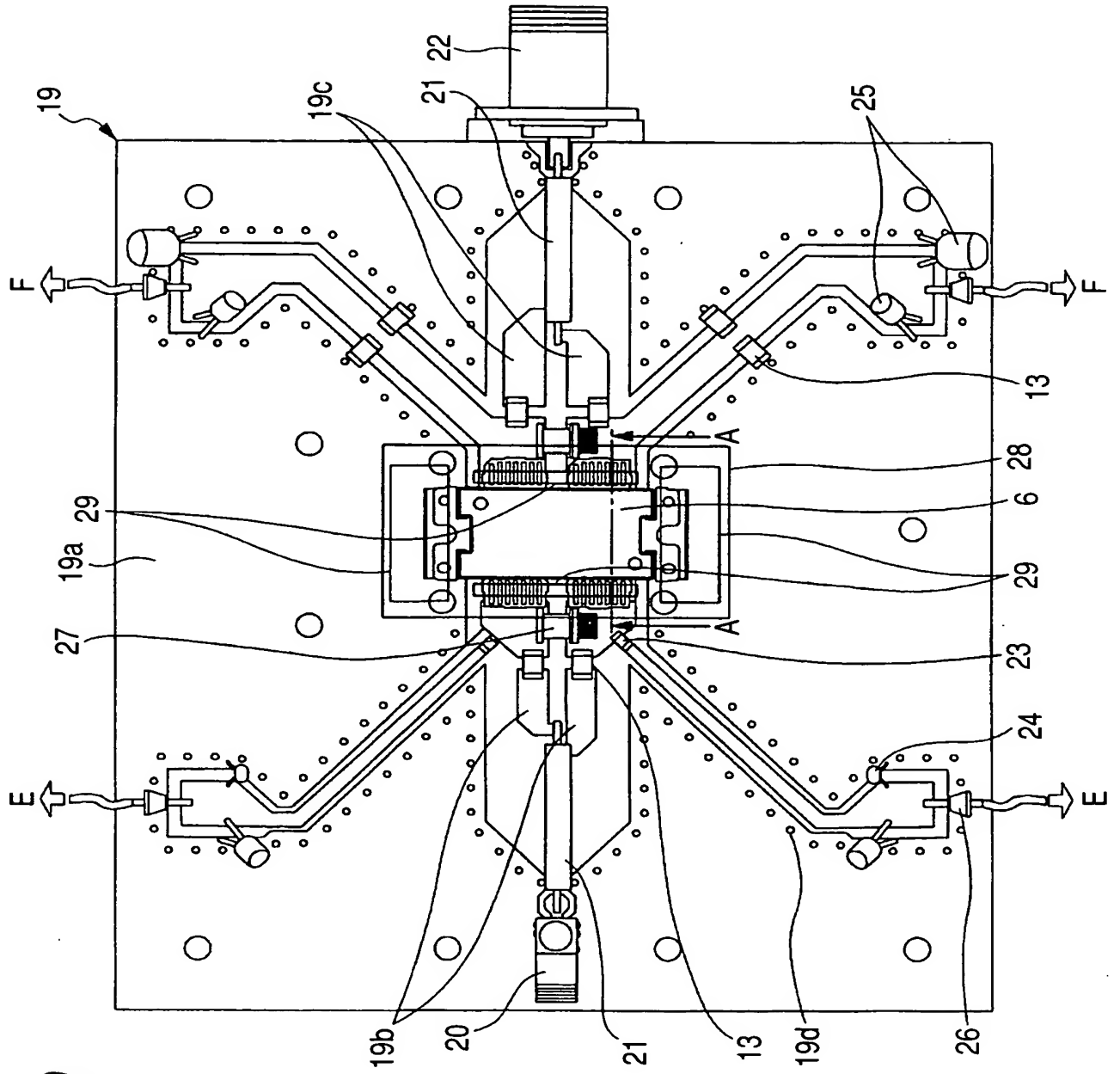


FIG. 29

FIG. 30

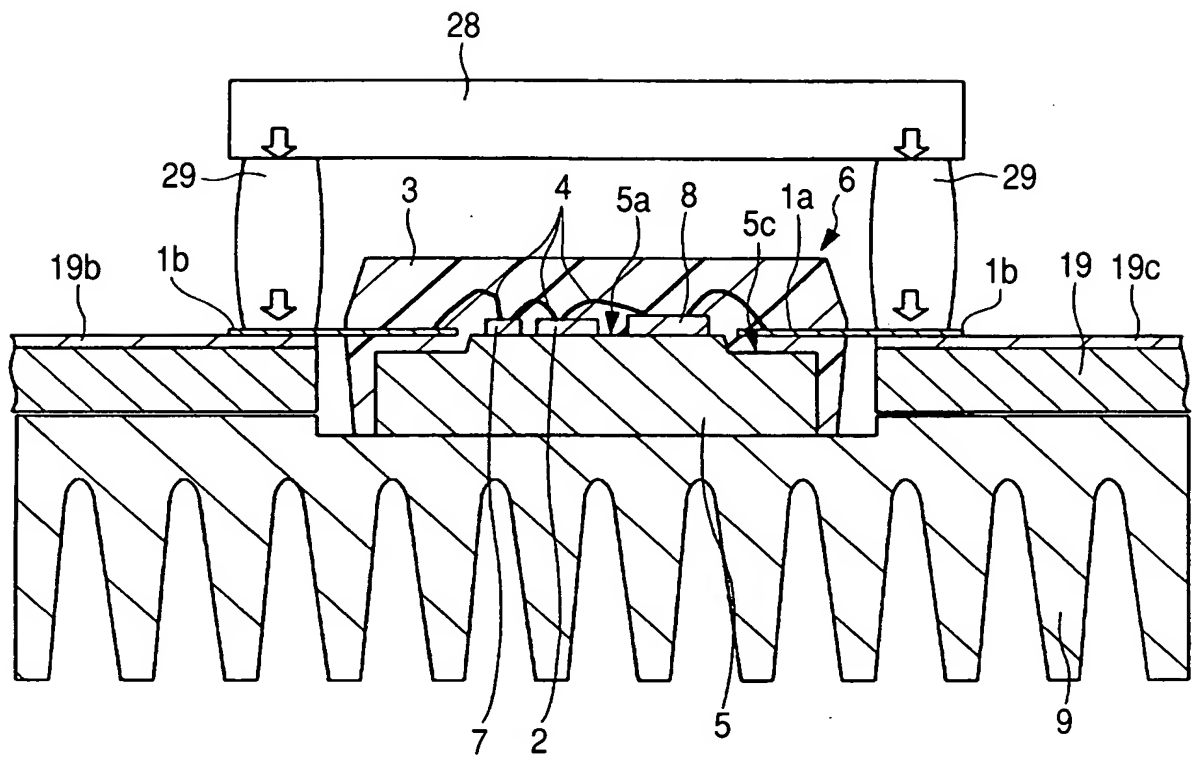


FIG. 31

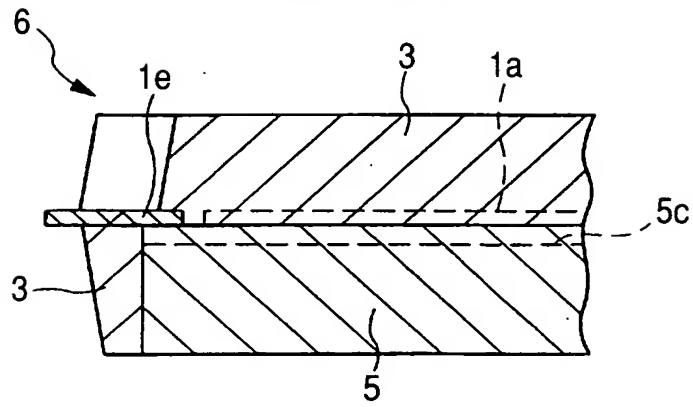


FIG. 32

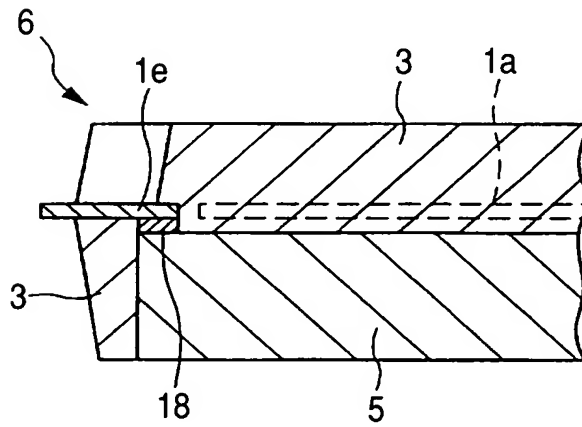


FIG. 33

